Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2993

Chopper Regulator, DC-DC Converter and Motor Drive **Applications**

• Low drain-source ON resistance $: R_{DS}(ON) = 82 \text{ m}\Omega \text{ (typ.)}$ High forward transfer admittance $|Y_{fs}| = 20 \text{ S (typ.)}$ Low leakage current $:IDSS = 100 \mu A \text{ (max) (V}DS = 250 \text{ V)}$ Enhancement-mode: $V_{th} = 1.5 \sim 3.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

Characteristics S		ymbol	Rating	Unit	
Drain-source voltage		V_{DSS}	250	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	250	V	
Gate-source voltage		V _{GSS} ±	20	V	
Drain current	DC (Not e 1)	I _D	20	Α	
	Pulse (Note 1)	I _{DP}	60		
Drain power dissipation (Tc = 25°C)		P _D 100		W	
Single pulse avalanche energy (Not e 2)		E _{AS} 423		mJ	
Avalanche current		I _{AR}	20	Α	
Repetitive avalanche energy (Note 3)		E _{AR} 10		mJ	
Channel temperature		T _{ch} 150		°C	
Storage temperature range		T _{stg}	−55~150 °	С	

Thermal Characteristics

Characteristics S	ymbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)} 1.	25	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)} 83	. 3	°C/W

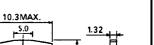
Note 1: Please u se d evices o n condition that the channel temperature is below 150°C.

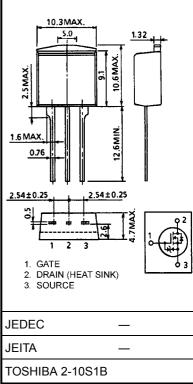
Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 1.79 mH, $I_{AR} = 20 \text{ A}$, $R_G = 25 \Omega$

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

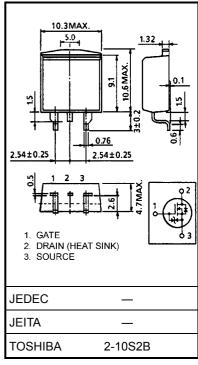
This transistor is an electrostatic sensitive device.

Please handle with caution.





Weight: 1.5 g (typ.)



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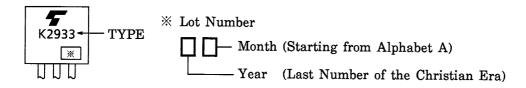
Electrical Characteristics (Ta = 25°C)

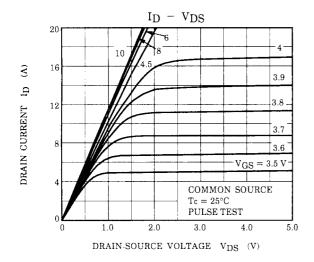
Charac	teristics S	ymbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μA
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V	_		100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	250	_	-	V
Gate threshold v	roltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.5		3.5	٧
Drain-source OI	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 10 A	_	82	105	mΩ
Forward transfer	admittance	Y _{fs} V	_{DS} = 10 V, I _D = 10 A	10	20	1	S
Input capacitano	е	C _{iss} —			4000	-	
Reverse transfer	capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		300	-	pF
Output capacitance		Coss]		— 1000		
Switching time	Rise time	t _r —	$V_{GS} \stackrel{10V}{\circ}_{OV} $		15		- ns
	Turn-on time	t _{on}		_	35	_	
	Fall time	t _f			30	_	
	Turn-off time	t _{off}	$V_{DD} \stackrel{.}{=} 130V$ Duty $\leq 1\%$, $t_w = 10 \mu s$	— 180 —			
Total gate charge (gate-source plus gate-drain)		Qg		— 10	0 —		_
Gate-source charge		Q _{gs}	$V_{DD} \approx 200 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		70	_	nC
Gate-drain ("miller") Charge		Q_{gd}					

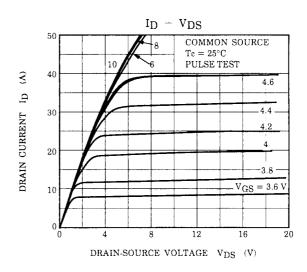
Source-Drain Ratings and Characteristics (Ta = 25°C)

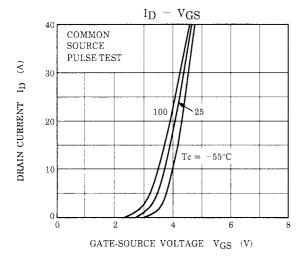
Characteristics S	ymbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Not e 1)	I _{DR} —		1		20	Α
Pulse drain reverse current (Not e 1)	I _{DRP} —		_		60	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 20 A, V _{GS} = 0 V	_	_	-2.0	V
Reverse recovery time	t _{rr}	I _{DR} = 20 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs		300	_	ns
Reverse recovery charge	Q _{rr}		— 3.	3 —		μC

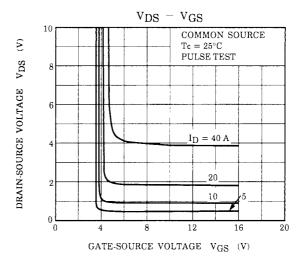
Marking

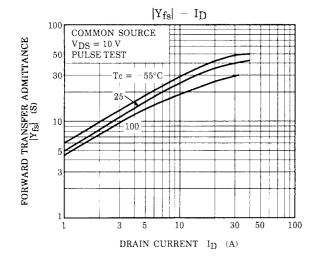


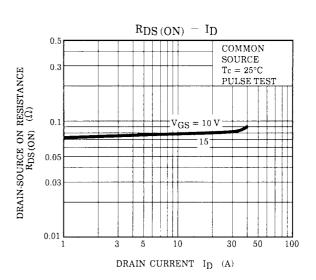




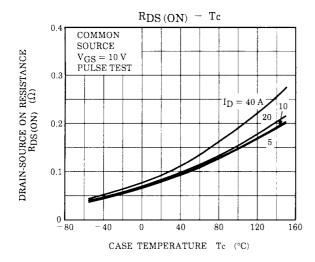


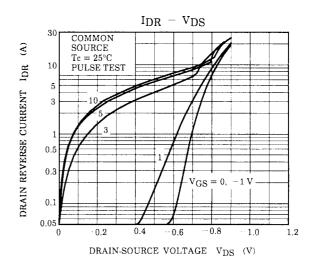


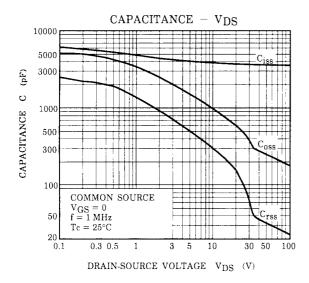


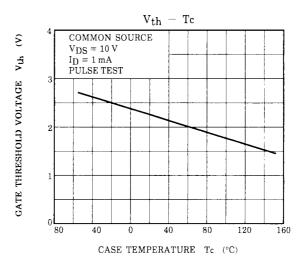


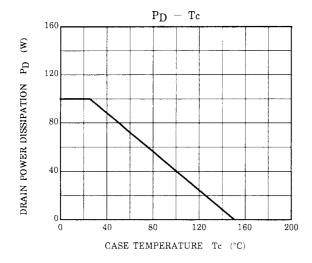
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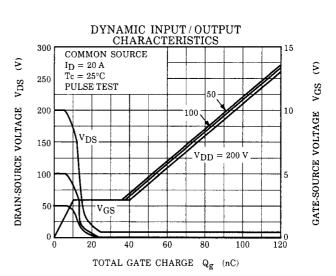




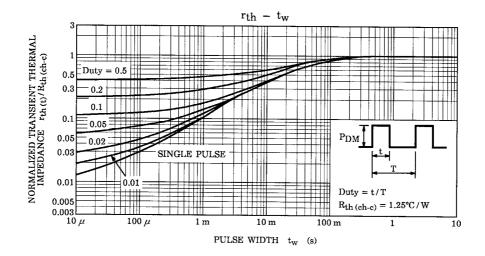


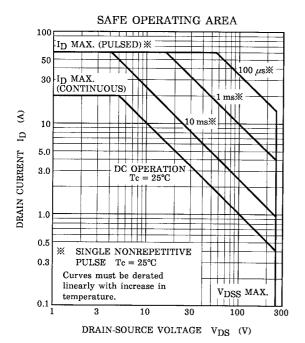


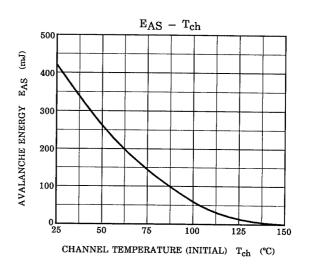


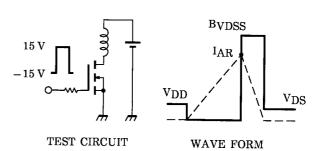


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$$\begin{aligned} &RG = 25~\Omega \\ &V_{DD} = 90~V,~L = 1.79~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BV_{DSS}}{BV_{DSS} - V_{DD}} \right)$$

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